



Features

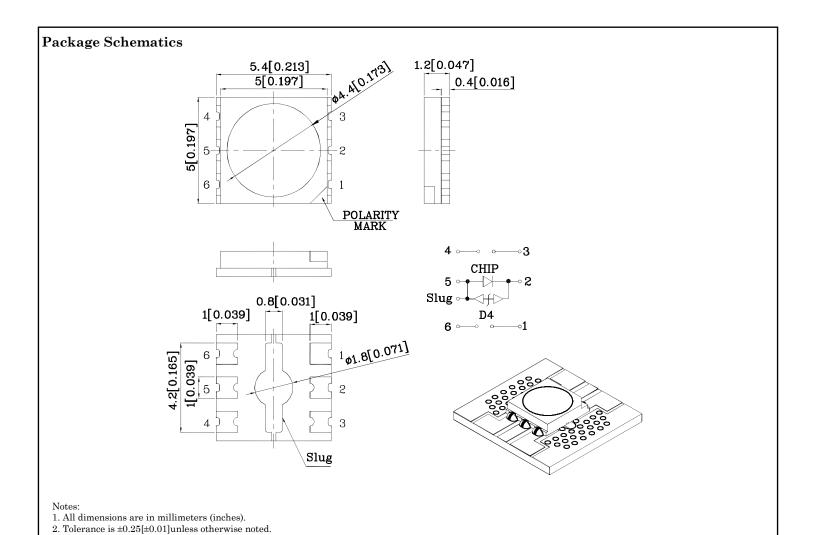
- \bullet 5.0mm X 5.0mm X 1.2mm SMD LED
- Zener diode provided for ESD protection
- IR-reflow compatible
- Standard Package: 500pcs / Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE

DEVICES



Dec 28,2013

3. Specifications are subject to change without notice.

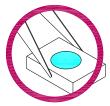


Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

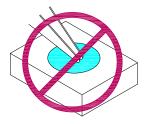
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

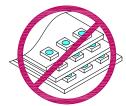


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

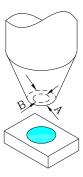




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



- 4.1. The inner diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks.
- 4.2. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
- 4.3. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



5. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

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Part Number: XZDG10X146S





Part Number	Dice Leng-color		7-2007* 0mA) [2]	$\begin{array}{c} \text{Luminous Flux} \\ \text{CIE}127\text{-}2007* \\ \text{(I}_{\text{F}}\!\!=\!\!350\text{mA})[2] \\ \text{lm} \end{array}$		Viewing Angle 2 0 1/2 [1]	
			Min.	Typ.	Min.	Typ.	
XZDG10X146S	Green (AlGaInN)	Water Clear	10*	13.49*	35*	47.7*	120°

Notes:

Absolute Maximum Ratings at TA=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	PD	1.33	W
DC Forward Current [1]	IF	350	mA
Peak Forward Current [2]	IFP	500	mA
Reverse Voltage	VR	5	V
Junction temperature	TJ	110	°C
Operating Temperature	Тор	-40 To +100	°C
Storage Temperature	Tstg	-40 To +110	°C
Thermal Resistance [1]	Rth j-a	78	°C/W

Notes:

Electrical / Optical Characteristics at Ta=25°C

Parameter	Symbol	Value	Unit	
Wavelength at peak emission IF = 350 mA CIE127- 2007 * [Typ.]	λpeak	520*	nm	
Dominant Wavelength IF = 350mA CIE127-2007* [Typ.]	λdom [1]	530*	nm	
Spectral bandwidth at 50% Φ REL MAX $$ If = 350mA $$ [Typ.]	$\triangle \lambda$	35	nm	
Forward Voltage IF=350mA [Min.]		2.7	V	
Forward Voltage IF=350mA [Typ.]	VF [2]	3.3		
Forward Voltage IF=350mA [Max.]		3.8		
Allowable Reverse Current [Max.]	IR	85	mA	
Temperature coefficient of λ peak IF = 350mA, - 10°C \leq T \leq 100°C [Typ.]	TCλpeak	0.16	nm/°C	
Temperature coefficient of λ dom IF = 350mA, \cdot 10°C \leq T \leq 100°C [Typ.]	TCλdom	0.14	nm/°C	
Temperature coefficient of VF $I_F = 350 \text{mA}, -10 \text{°C} \leq T \leq 100 \text{°C} \text{ [Typ.]}$	TCv	-3.1	mV/°C	

Notes:

1.Wavelength: +/-1nm.

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XDSB6148 V4-Z Layout: Maggie L.

 $^{1. \}theta 1/2$ is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

 $^{2.\} Luminous\ intensity\ /\ luminous\ flux: +/-15\%.\ LEDs\ are\ binned\ according\ to\ their\ luminous\ flux.$

^{*}Luminous intensity / luminous flux value is in accordance with CIE127-2007 standards.

^{1.} Results from mounting on metal core PCB, mounted on pc board-metal core PCB is recommend for lowest thermal resistance.

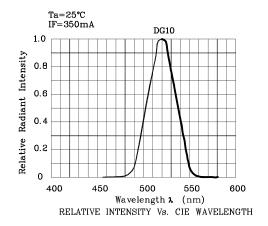
^{2. 1/10} Duty Cycle, 0.1ms Pulse Width.

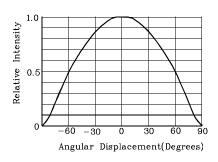
^{2.} Forward Voltage: +/-0.1V.

 $[\]mbox{*}$ Wavelength value is in accordance with CIE127-2007 standards.

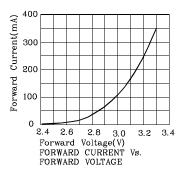


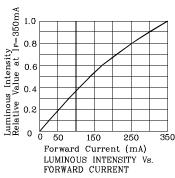


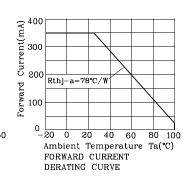


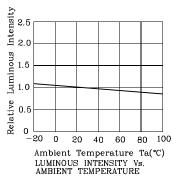


❖ DG10



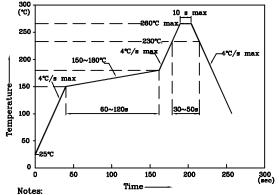






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

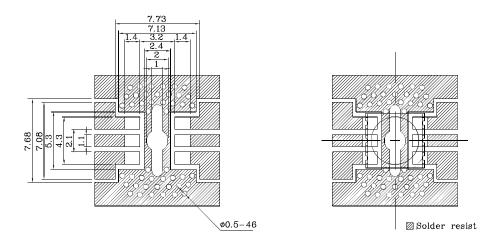


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

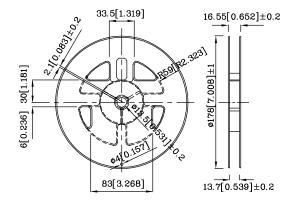




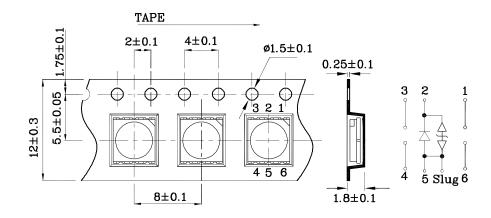
♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



* Reel Dimension



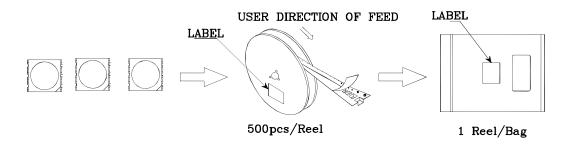
Tape Specification (Units:mm)

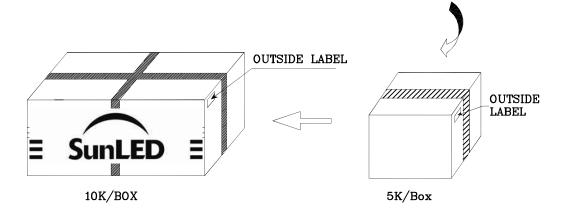


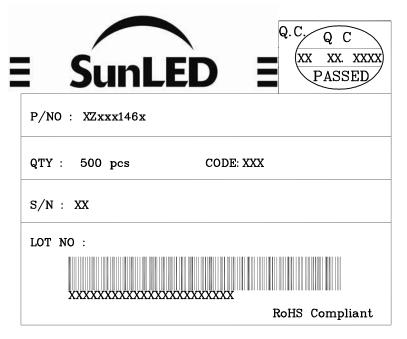




PACKING & LABEL SPECIFICATIONS







TERMS OF USE

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Dec 28,2013